

PACKAGE: MLP16 3.0 x 3.0 (GREEN)

MATERIALS DECLARATION:

No.	Part Name	Material Name	Component wt (mg)	Material Content (Element)	CAS Number	Element Wt (%)	Element Wt (mg)	Wt % Of Total Unit Wt	ppm
1	Leadframe	Copper A194 PEH	4.0211	Cu	7440-50-8	97.5	3.9206	17.7982	177982.38
				Fe	7439-89-6	2.35	0.0945	0.4290	4289.83
				Zn	7440-66-6	0.12	0.0048	0.0219	219.06
				P	7723-14-0	0.03	0.0012	0.0055	54.76
				Ag (B)	7440-22-4	100	0.1341	0.6089	6089.05
2	Die attach material	Sumitomo CRM1076DJ	0.1252	Silver (65 - 85)	7440-22-4	75	0.0939	0.4263	4262.78
				Epoxy Resin (15 - 25)	9003-36-5	20	0.0250	0.1137	1136.74
				t-Butyl phenyl glycidyl	3101-60-8	7.5	0.0094	0.0426	426.28
				Phenolic hardener(1 - 2)	92-88-6	1.5	0.0019	0.0085	85.26
				Butyl cellosolve acetate	112-07-2	1	0.0013	0.0057	56.84
3	Gold Wire	Gold	0.0458	Au	7440-57-5	99.99	0.0457	0.2077	2076.71
4	Tin Plate	Pure Tin	0.3343	Sn	7440-31-5	100	0.3343	1.5177	15177.26
5	Mold Compound	Sumitomo G770HT/CD	16.8785	Silica Fused (85 - 95)	60676-86-0	90	15.1906	68.9609	689609.19
				Epoxy Resin (1 - 5)	Trade secret	3	0.5064	2.2987	22986.97
				Phenol Resin (1 - 5)	Trade secret	3	0.5064	2.2987	22986.97
				Carbon Black (0.1- 0.5)	1333-86-4	0.3	0.0506	0.2299	2298.70
6	Die	Silicon Die	0.4889				0.4889	2.2195	22194.58
Total unit weight =			22.0279						

PACKAGE: MLP8 2.0 x 2.0 (GREEN)

MATERIALS DECLARATION:

No.	Part Name	Material Name	Component wt (mg)	Material Content (Element)	CAS Number	Element Wt (%)	Element Wt (mg)	Wt % Of Total Unit Wt	ppm
1	Leadframe	Copper A194 PEH	0.7722	Cu	7440-50-8	97.5	0.7529	32.9495	329494.67
				Fe	7439-89-6	2.35	0.0181	0.7942	7941.67
				Zn	7440-66-6	0.12	0.0009	0.0406	405.53
				P	7723-14-0	0.03	0.0002	0.0101	101.38
2	Die attach material	Screen print 8006NS	0.0199	Aluminium Oxide	1344-28-1	50	0.0099	0.4352	4352.04
				2-(2-Ethoxyetho	112-15-2	20	0.0040	0.1741	1740.82
				Phenol, 4,4'-(1-methylethylidene	25036-25-3	20	0.0040	0.1741	1740.82
				Epoxy resin	25068-38-6	5	0.0010	0.0435	435.20
				Aromatic Amine	Proprietary	5	0.0010	0.0435	435.20
3	Gold Wire	Gold	0.0147	Au	7440-57-5	99.99	0.0147	0.6443	6442.78
				Others	Proprietary	0.01	0.0000	0.0001	0.64
4	Internal Plating	NiPdAu	0.0049	Ni	7440-02-0	92.23	0.00450	0.1970	1969.63
				Pd	7440-05-3	7.47	0.00036	0.0160	159.57
				Au	7440-57-5	0.30	0.00001	0.0006	6.41
5	External Plating	NiPdAu	0.0065	Ni	7440-02-0	92.23	0.0060	0.2611	2610.91
				Pd	7440-05-3	7.47	0.0005	0.0212	211.52
				Au	7440-57-5	0.30	0.00002	0.0008	8.50
6	Mold Compound	EME G770HCD	1.2963	Silica Fused	60676-86-0	91.7	1.1888	52.0258	520257.89
				Epoxy Resin	Trade secret	4	0.0519	2.2694	22693.91
				Phenol Resin	Trade secret	4	0.0519	2.2694	22693.91
				Carbon Black	1333-86-4	0.3	0.0039	0.1702	1702.04
7	Die	Silicon Die	0.1704				0.1704	7.4595	74594.94
Total unit weight =			2.2849						

PACKAGE: MSOP8 (GREEN)

MATERIALS DECLARATION:

No.	Part Name	Material Name	Component wt (mg)	Material Content (Element)	CAS Number	Element Wt (%)	Element Wt (mg)	Wt % Of Total Unit Wt	ppm
1	Leadframe	Copper A194 PEH	0.7722	Cu	7440-50-8	97.5	0.7529	32.9495	329494.67
				Fe	7439-89-6	2.35	0.0181	0.7942	7941.67
				Zn	7440-66-6	0.12	0.0009	0.0406	405.53
				P	7723-14-0	0.03	0.0002	0.0101	101.38
2	Die attach material	Screen print 8006NS	0.0199	Aluminium Oxide	1344-28-1	50	0.0099	0.4352	4352.04
				2-(2-Ethoxyetho	112-15-2	20	0.0040	0.1741	1740.82
				Phenol, 4,4'-(1-methylethylidene	25036-25-3	20	0.0040	0.1741	1740.82
				Epoxy resin	25068-38-6	5	0.0010	0.0435	435.20
				Aromatic Amine	Proprietary	5	0.0010	0.0435	435.20
3	Gold Wire	Gold	0.0147	Au	7440-57-5	99.99	0.0147	0.6443	6442.78
				Others	Proprietary	0.01	0.0000	0.0001	0.64
4	Internal Plating	NiPdAu	0.0049	Ni	7440-02-0	92.23	0.00450	0.1970	1969.63
				Pd	7440-05-3	7.47	0.00036	0.0160	159.57
				Au	7440-57-5	0.30	0.00001	0.0006	6.41
5	External Plating	NiPdAu	0.0065	Ni	7440-02-0	92.23	0.0060	0.2611	2610.91
				Pd	7440-05-3	7.47	0.0005	0.0212	211.52
				Au	7440-57-5	0.30	0.00002	0.0008	8.50
6	Mold Compound	EME G770HCD	1.2963	Silica Fused	60676-86-0	91.7	1.1888	52.0258	520257.89
				Epoxy Resin	Trade secret	4	0.0519	2.2694	22693.91
				Phenol Resin	Trade secret	4	0.0519	2.2694	22693.91
				Carbon Black	1333-86-4	0.3	0.0039	0.1702	1702.04
7	Die	Silicon Die	0.1704				0.1704	7.4595	74594.94
Total unit weight =			2.2849						

PACKAGE: MSOP10 (GREEN)

MATERIALS DECLARATION:

No.	Part Name	Material Name	Component wt (mg)	Material Content (Element)	CAS Number	Element Wt (%)	Element Wt (mg)	Wt % Of Total Unit Wt	ppm
1	Leadframe	Copper A194 PEH	0.7722	Cu	7440-50-8	97.5	0.7529	32.9495	329494.67
				Fe	7439-89-6	2.35	0.0181	0.7942	7941.67
				Zn	7440-66-6	0.12	0.0009	0.0406	405.53
				P	7723-14-0	0.03	0.0002	0.0101	101.38
2	Die attach material	Screen print 8006NS	0.0199	Aluminium Oxide	1344-28-1	50	0.0099	0.4352	4352.04
				2-(2-Ethoxyetho	112-15-2	20	0.0040	0.1741	1740.82
				Phenol, 4,4'-(1-methylethylidene	25036-25-3	20	0.0040	0.1741	1740.82
				Epoxy resin	25068-38-6	5	0.0010	0.0435	435.20
				Aromatic Amine	Proprietary	5	0.0010	0.0435	435.20
3	Gold Wire	Gold	0.0147	Au	7440-57-5	99.99	0.0147	0.6443	6442.78
				Others	Proprietary	0.01	0.0000	0.0001	0.64
4	Internal Plating	NiPdAu	0.0049	Ni	7440-02-0	92.23	0.00450	0.1970	1969.63
				Pd	7440-05-3	7.47	0.00036	0.0160	159.57
				Au	7440-57-5	0.30	0.00001	0.0006	6.41
5	External Plating	NiPdAu	0.0065	Ni	7440-02-0	92.23	0.0060	0.2611	2610.91
				Pd	7440-05-3	7.47	0.0005	0.0212	211.52
				Au	7440-57-5	0.30	0.00002	0.0008	8.50
6	Mold Compound	EME G770HCD	1.2963	Silica Fused	60676-86-0	91.7	1.1888	52.0258	520257.89
				Epoxy Resin	Trade secret	4	0.0519	2.2694	22693.91
				Phenol Resin	Trade secret	4	0.0519	2.2694	22693.91
				Carbon Black	1333-86-4	0.3	0.0039	0.1702	1702.04
7	Die	Silicon Die	0.1704				0.1704	7.4595	74594.94
Total unit weight =			2.2849						

REVISION HISTORY

Revision	Date	Description
A	3/4/2014	Initial Release